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T-1 (3mm) SOLID STATE LAMP

Part Number: WP710A10NT Pure Orange

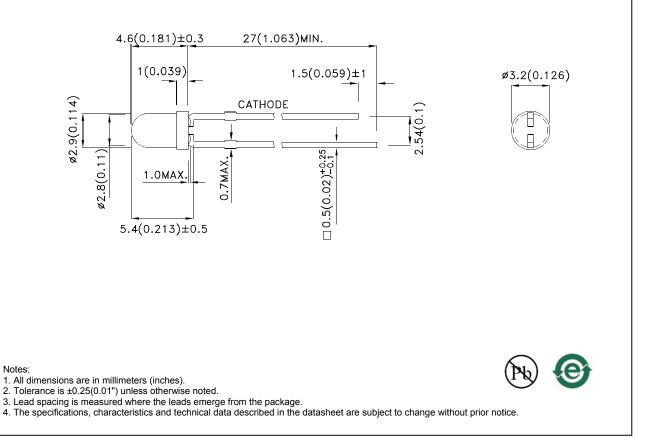
Features

- Low power consumption.
- Popular T-1 diameter package.
- General purpose leads.
- Reliable and rugged.
- Long life solid state reliability.
- Available on tape and reel.
- RoHS compliant.

Description

The Pure Orange source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Pure Orange Light Emitting Diode.

Package Dimensions



SPEC NO: DSAL0516 APPROVED: WYNEC REV NO: V.3A CHECKED: Allen Liu DATE: FEB/17/2013 DRAWN: Y.Liu PAGE: 1 OF 6 ERP: 1101029070

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 10mA		Viewing Angle [1]
			Min.	Тур.	201/2
WP710A10NT	Pure Orange (GaAsP/GaP)	Orange Transparent	15	40	- 34°
			*12	*30	

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.

2. Luminous intensity/ luminous Flux: +/-15%.

*Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions	
λpeak	Peak Wavelength	Pure Orange	607		nm	I⊧=20mA	
λD [1]	Dominant Wavelength	Pure Orange	602		nm	I⊧=20mA	
Δλ1/2	Spectral Line Half-width	Pure Orange	35		nm	I⊧=20mA	
С	Capacitance	Pure Orange	15		pF	V⊧=0V;f=1MHz	
VF [2]	Forward Voltage	Pure Orange	2.05	2.5	V	IF=20mA	
lr	Reverse Current	Pure Orange		10	uA	VR = 5V	

Notes:

1.Wavelength: +/-1nm.

2.Forward Voltage: +/-0.1V.

3. Wavelength value is traceable to the CIE127-2007 compliant national standards.

Parameter **Pure Orange** Units Power dissipation 62.5 mW DC Forward Current 25 mΑ Peak Forward Current [1] 145 mΑ 5 V Reverse Voltage -40°C To +85°C Operating/Storage Temperature Lead Solder Temperature [2] 260°C For 3 Seconds Lead Solder Temperature [3] 260°C For 5 Seconds

Absolute Maximum Ratings at TA=25°C

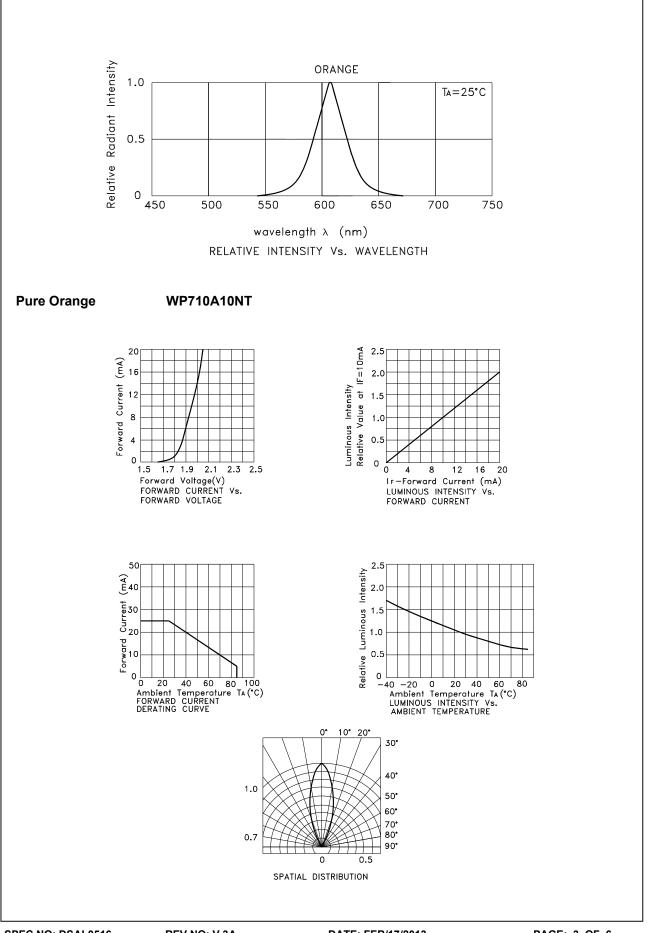
Notes:

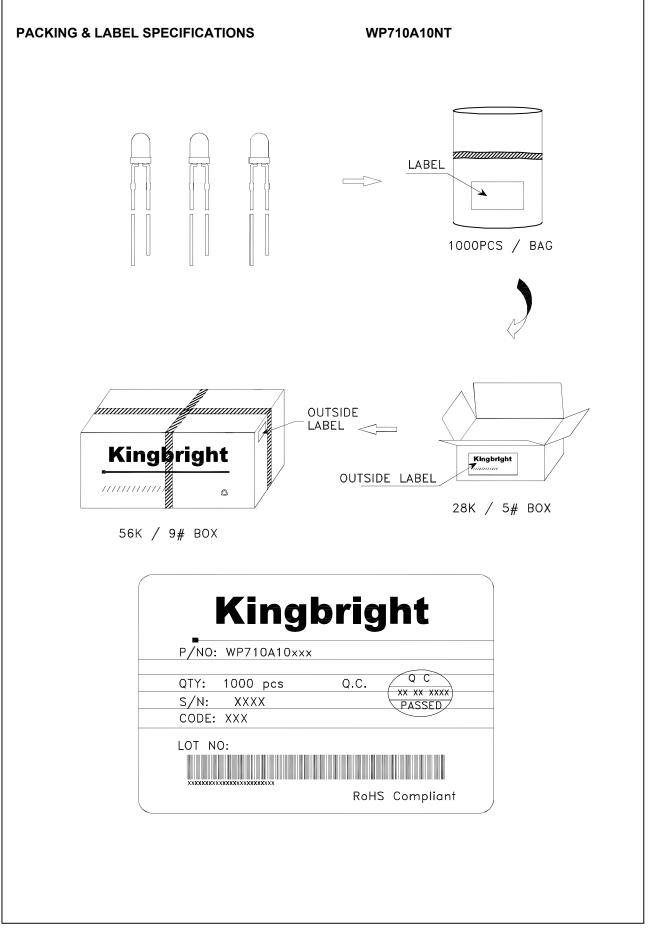
1. 1/10 Duty Cycle, 0.1ms Pulse Width.

2. 2mm below package base.

3. 5mm below package base.

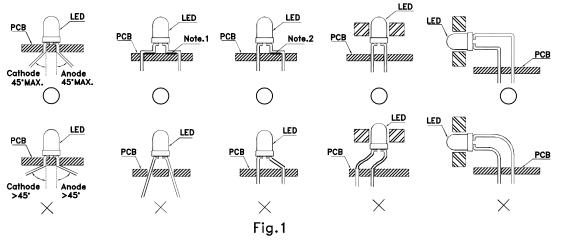
DATE: FEB/17/2013 DRAWN: Y.Liu





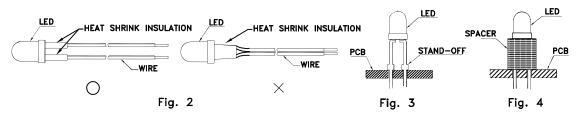
PRECAUTIONS

1. The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

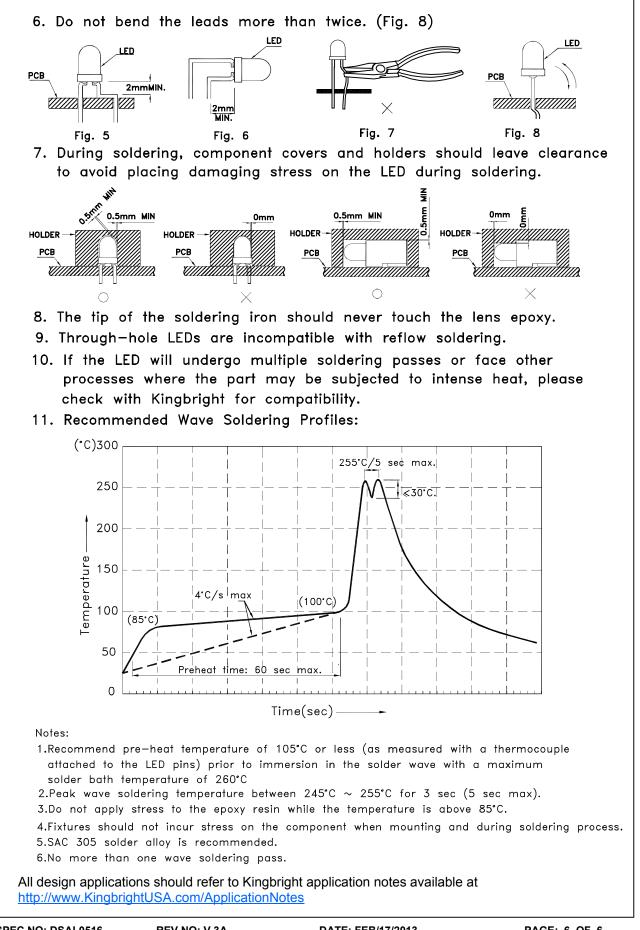


" \bigcirc " Correct mounting method "imes" Incorrect mounting method

- 2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig.2)
- 3. Use stand-offs (Fig.3) or spacers (Fig.4) to securely position the LED above the PCB.



- 4. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)
- 5. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)



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